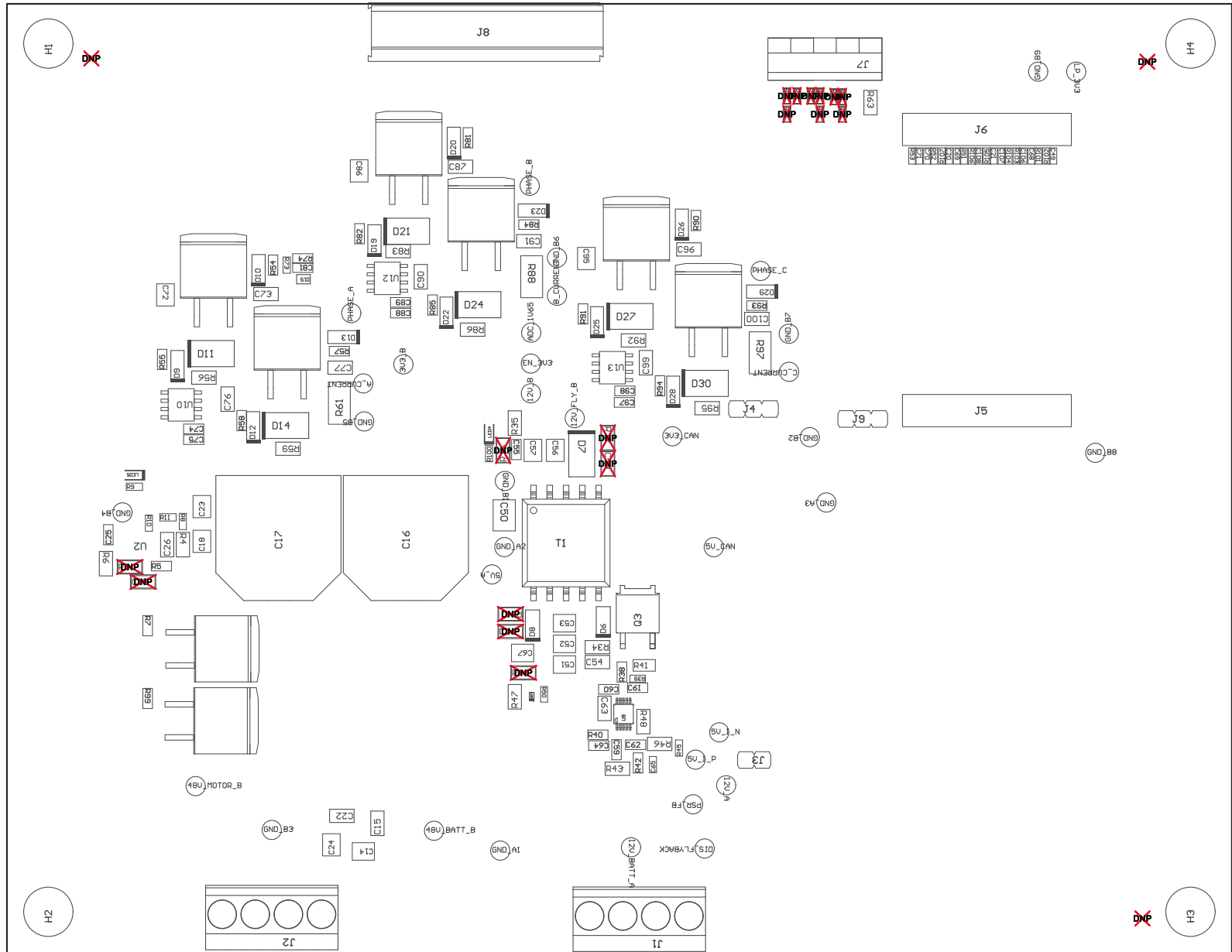
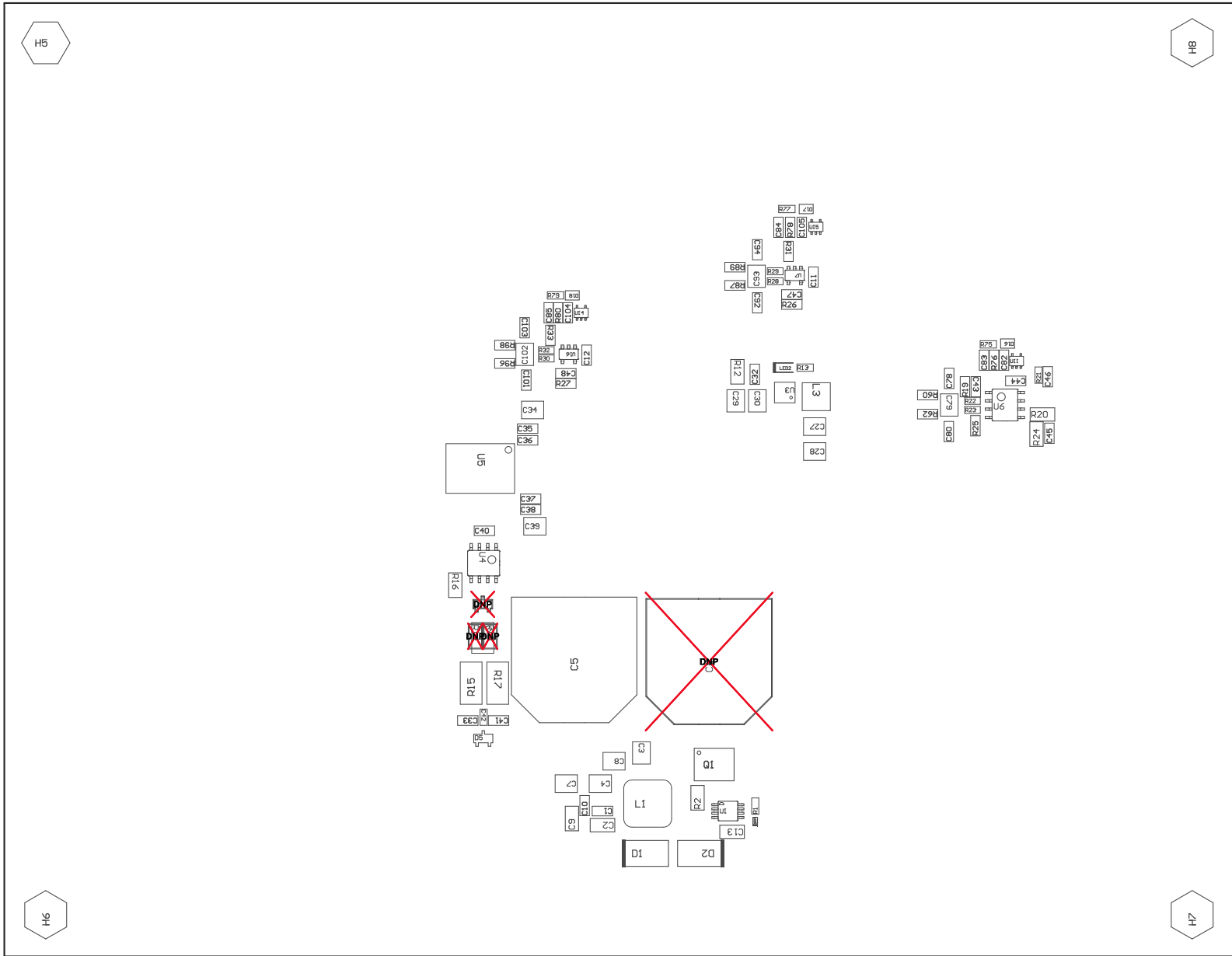


Z21 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
 Z22 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
 Z23 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
 Z24 ■ J5 and J6, SSM-110-23-F-D, connectors are to be installed on the bottom of the PCB. This means the male leads of J5 and J6 will be visible from the top and the female from the bottom.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00281	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-00281		
PLOT NAME = Top Assembly Drawing	GENERATED : 10/23/2015 3:39:25 PM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00281	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-00281		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 10/23/2015 3:39:30 PM		TEXAS INSTRUMENTS

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